

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Makoto Aikawa	06/06/2006
RECEIVING PARTY DATA	
Name:	Sony Computer Entertainment Inc.
Street Address:	2-6-21 Minami-Aoyama, Minato-Ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	107-0062
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11424613
CORRESPONDENCE DATA	
Fax Number:	(512)823-1036
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	5128239667
Email:	Beth_Neely@us.ibm.com
Correspondent Name:	Diana R. Gerhardt
Address Line 1:	11400 Burnet Road
Address Line 2:	IBM-Intellectual Property Law
Address Line 4:	Austin, TEXAS 78758-3493
ATTORNEY DOCKET NUMBER:	AUS920060067US1
NAME OF SUBMITTER:	Diana R. Gerhardt
Total Attachments: 1 source=assignment-Sony#page1.tif	

CH \$40.00 11424613

STI # 1758
IBM Docket No. AUS920060067US1

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in: Impedance Measurement of Chip, Package, and Board Power Supply System Using Pseudo Impulse Response

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Computer Entertainment Inc., a Japanese corporation with offices at 2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062, Japan, (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said applications, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patent, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said applications for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale,

This assignment executed on the dates indicated below.

Makoto Aikawa

Name of First or Sole Inventor

c/o Sony Computer Entertainment Inc. 2-21-6, Minami-Aoyama, Minato-ku, Tokyo, Japan 107-0062

Residence of First or Sole Inventor

(Signature)
Signature of First or Sole Inventor

6th, June, 2006
Date of this Assignment

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